

L Number	Hits	Search Text	DB	Time stamp
1	2	((("5497545") or ("5654590"))).PN.	USPAT	2002/12/24 17:39
2	1	("5965933").PN.	USPAT	2002/12/24 18:19
3	45	silicon near interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:20
4	45	(silicon near interposer) and (package or chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:32
5	5	438/977.ccls. and (pcb or pwb or (printed near board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:36
6	72	438/977.ccls. and (package or pcb or pwb or (printed near board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:36
7	67	(438/977.ccls. and (package or pcb or pwb or (printed near board))) not (438/977.ccls. and (pcb or pwb or (printed near board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:51
8	4174	(silicon near wafer) and (wafer near (thin\$4 or remov\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:20
9	732	((silicon near wafer) and (wafer near (thin\$4 or remov\$4))) and (package or mount)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:53
10	1	((silicon near wafer) and (wafer near (thin\$4 or remov\$4))) and (package or mount) and sbp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:54
11	1	((silicon near wafer) and (wafer near (thin\$4 or remov\$4))) and (package or mount) and utsw	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 18:54
12	663	((silicon near wafer) and (wafer near (thin\$4 or remov\$4))) and (package or mount) and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:59
13	84805	(silicon near (base or substrate or wafer)) and ((thin\$4 or remov\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:31
14	1	("6423643").PN.	USPAT	2002/12/24 19:23
15	1	("5847458").PN.	USPAT	2002/12/24 19:24
16	1	("6411502").PN.	USPAT	2002/12/24 19:24
17	1	("6441502").PN.	USPAT	2002/12/24 19:25
18	1	("5900676").PN.	USPAT	2002/12/24 19:25
19	1	((("5847458").PN.) and (package or mount)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 19:27



36	661	438/for.340.ccls. and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:33
37	0	438/106.ccls and (thin\$4 or remov\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:32
38	1165	438/106.ccls. and (thin\$4 or remov\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:34
39	1033	(438/106.ccls. and (thin\$4 or remov\$3)) and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:34
40	73	438/106.ccls. and ((thin\$4 or remov\$3) near (silicon or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:40
41	29	438/108.ccls. and ((thin\$4 or remov\$3) near (silicon or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:45
42	0	6420209.URPN.	USPAT	2002/12/24 20:42
43	0	6420209.URPN.	USPAT	2002/12/24 20:42
44	20	438/668.ccls. and ((thin\$4 or remov\$3) near (silicon or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:48
45	52	257/777.ccls. and ((thin\$4 or remov\$3) near (silicon or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:57
46	1229	((ball or bump or connect\$3) near wafer) and (chip or die or package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 20:59
47	1059	((ball or bump or connect\$3) near wafer) and (chip or die or package)) and (@ad<20010531)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 21:29
48	204	silicon with interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/24 21:31